

## Description

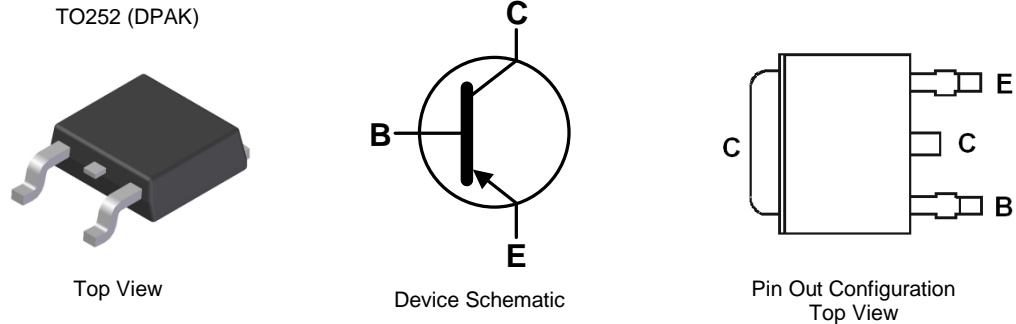
This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of Automotive Applications.

## Features

- $BV_{CE0} > -100V$
- $I_C = -3A$  High Continuous Collector Current
- $I_{CM} = -5A$  Peak Pulse Current
- Ideal for Power Switching or Amplification Applications
- Complementary NPN Type: MJD31CUQ
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

## Mechanical Data

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound  
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per  
MIL-STD-202, Method 208 ③
- Weight: 0.34 grams (Approximate)

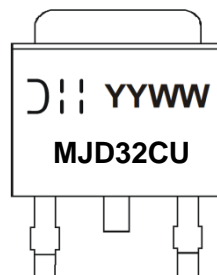


## Ordering Information (Notes 4 & 5)

Part number	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
MJD32CUQ-13	Automotive	MJD32CU	13	16	2,500

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to [http://www.diodes.com/product\\_compliance\\_definitions.html](http://www.diodes.com/product_compliance_definitions.html).
  5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



- MJD32CU = Product Type Marking Code  
 DII = Manufacturers' Code Marking  
 YYWW = Date Code Marking  
 YY = Last Two Digits of Year (ex: 17 = 2017)  
 WW = Week Code (01 to 53)

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-120	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-100	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	I <sub>C</sub>	-3	A
Peak Pulse Collector Current	I <sub>CM</sub>	-5	A
Continuous Base Current	I <sub>B</sub>	-1	A
Power Dissipation	P <sub>D</sub>	15	W

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

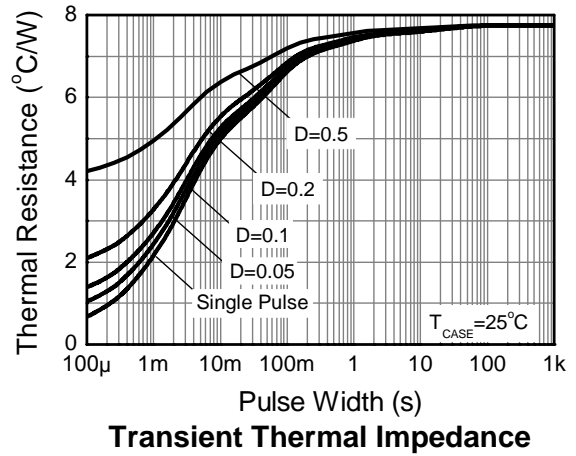
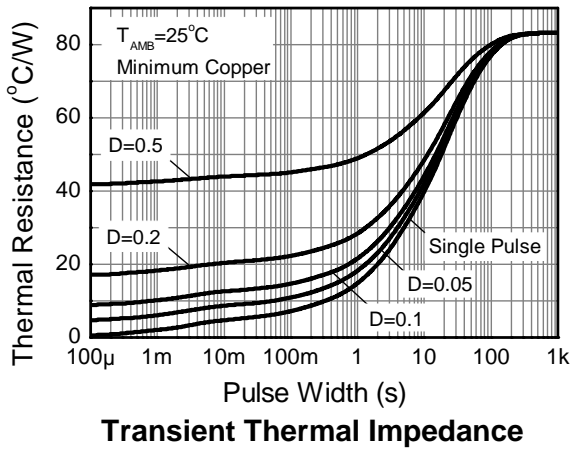
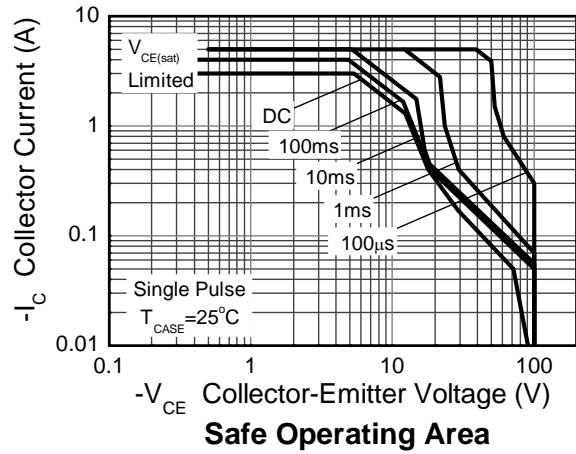
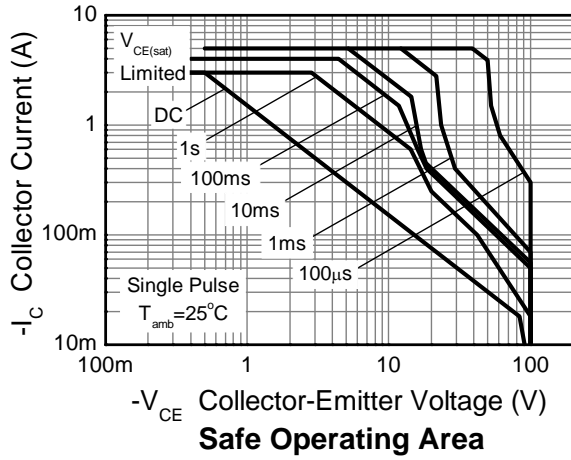
Characteristic	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	(Note 6)	3.9
		(Note 7)	2.1
		(Note 8)	1.6
Thermal Resistance, Junction to Ambient Air	R <sub>θJA</sub>	(Note 6)	32
		(Note 7)	59
		(Note 8)	80
Thermal Resistance, Junction to Leads	R <sub>θJL</sub>	3.6	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	

**ESD Ratings** (Note 10)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the exposed collector pad on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  7. Same as note (6), except mounted on 25mm x 25mm 1oz copper.
  8. Same as note (6), except mounted on minimum recommended pad (MRP) layout.
  9. Thermal resistance from junction to solder-point (on the exposed collector pad).
  10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

**Thermal Characteristics**

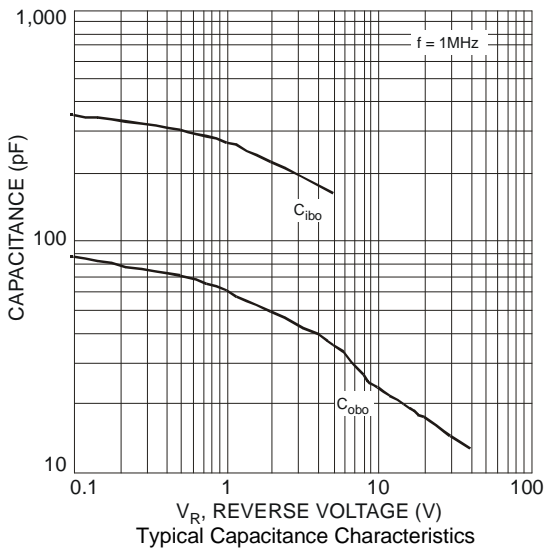
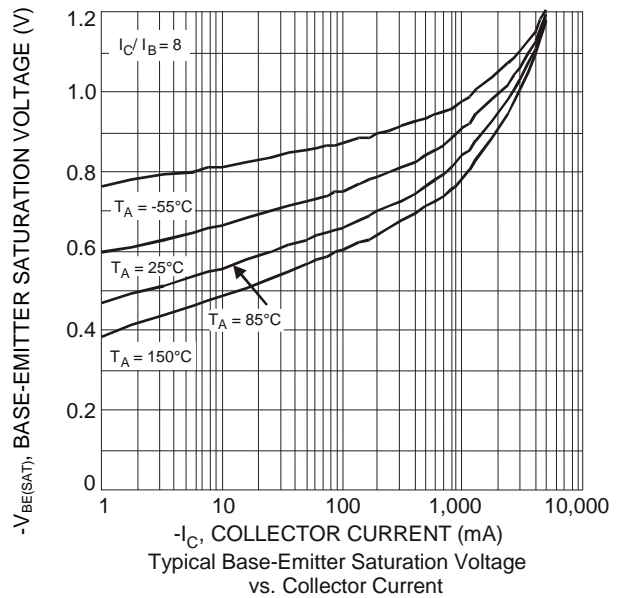
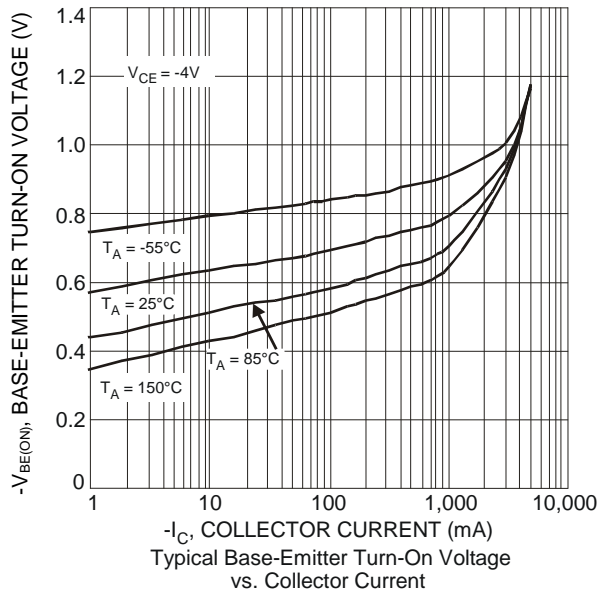
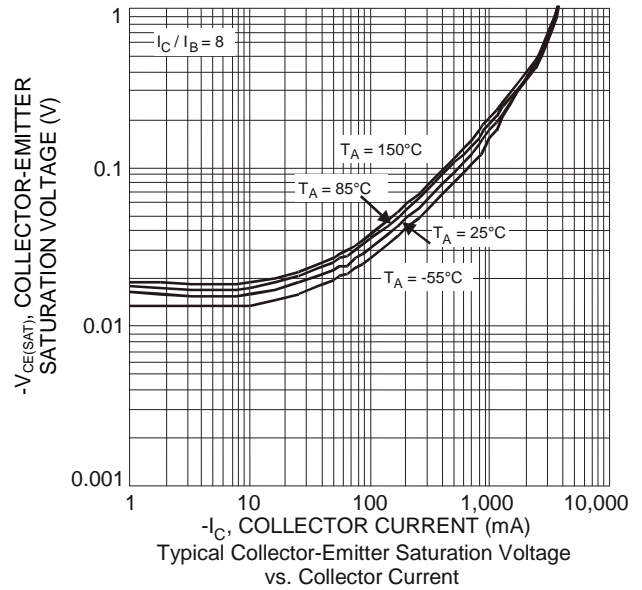
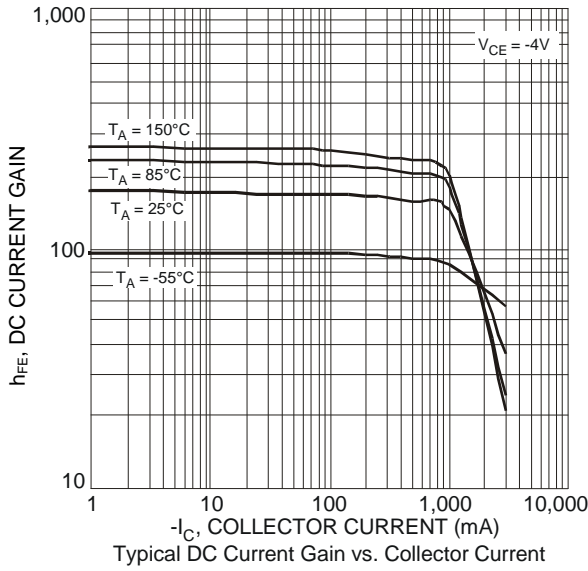


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	-120	-	-	V	$I_C = -20\mu A$
Collector-Emitter Breakdown Voltage (Note 11)	$BV_{CEO}$	-100	-	-	V	$I_C = -30mA$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-7	-	-	V	$I_E = -100\mu A$
Collector-Base Cut-off Current	$I_{CBO}$	-	-	-1	$\mu A$	$V_{CB} = -100V$
Collector Cut-off Current	$I_{CEO}$	-	-	-1	$\mu A$	$V_{CE} = -60V$
Collector Cut-off Current	$I_{CES}$	-	-	-1	$\mu A$	$V_{CE} = -100V$
Emitter Cut-off Current	$I_{EBO}$	-	-	-1	$\mu A$	$V_{EB} = -5V$
Collector-Emitter Saturation Voltage (Note 11)	$V_{CE(sat)}$	-	-	-300	mV	$I_C = -1A, I_B = -100mA$
		-	-	-500	mV	$I_C = -2A, I_B = -200mA$
		-	-	-700	mV	$I_C = -3A, I_B = -375mA$
Base-Emitter Saturation Voltage (Note 11)	$V_{BE(sat)}$	-	-	-1.2	V	$I_C = -2A, I_B = -200mA$
Base-Emitter Turn-On Voltage (Note 11)	$V_{BE(on)}$	-	-	-950	mV	$I_C = -1A, V_{CE} = -2V$
		-	-	-1.4	V	$I_C = -3A, V_{CE} = -4V$
DC Current Gain (Note 11)	$h_{FE}$	25	-	-	-	$V_{CE} = -4V, I_C = -1A$
		10	-	50	-	$V_{CE} = -4V, I_C = -3A$
Current Signal Current Gain	$H_{fe}$	20	-	-	-	$V_{CE} = -10V, I_C = -0.5A, f = 1kHz$
Current Gain-Bandwidth Product	$f_T$	3.0	-	-	MHz	$I_C = -0.5A, V_{CE} = -10V, f = 1MHz$

Note: 11. Measured under pulsed conditions. Pulse width  $\leq 300\mu s$ . Duty cycle  $\leq 2\%$ .

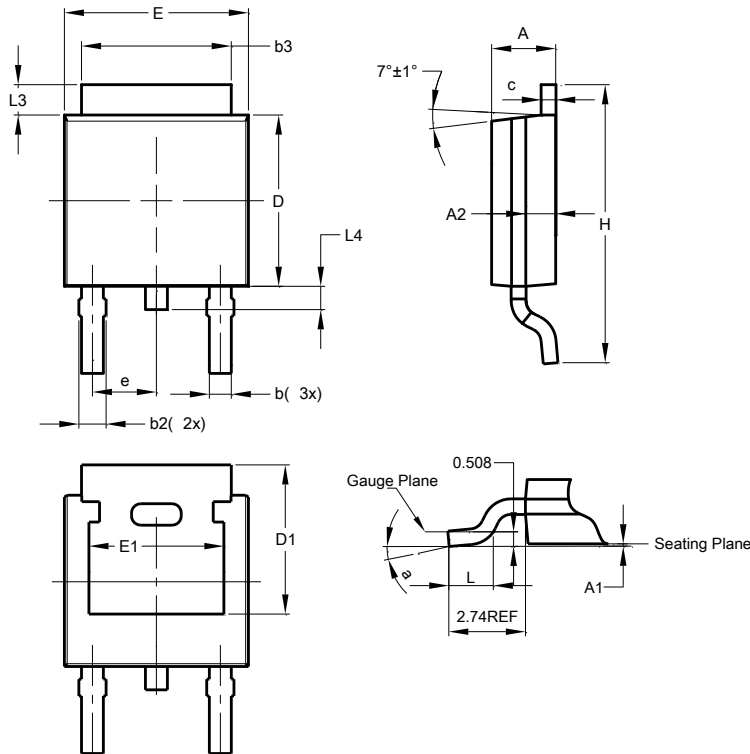
**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**TO252 (DPAK)**

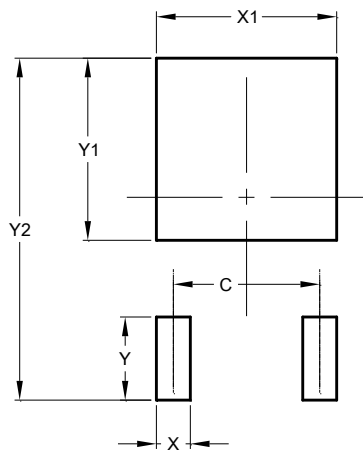


TO252 (DPAK)			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**TO252 (DPAK)**



Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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